

## REMARKS

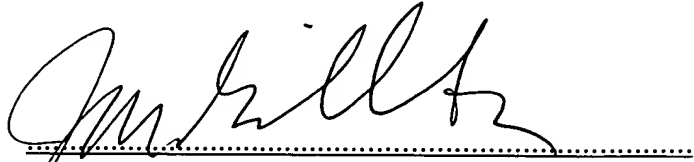
A Notice of Allowance was received in parent Application Serial No. 08/946,712, noting allowance of method claims for processing a diamond film substrate.

A comparison of the allowed independent method claim 1 and current pending claim 4 is shown in the table below. Pending claims 4-8 are believed to be patentable for the same reasons that method claim 1 was allowed.

Allowed Method Claim 1	Pending Claim 4
<p>A method for processing a diamond film substrate said method comprising:</p> <p>(a) applying a first wavelength of laser light to a diamond film substrate having a surface, said surface having an initial surface roughness, <math>R_0</math>, to both evaporate a portion of the substrate surface and create a structurally weakened surface having an intermediate surface roughness, <math>R_i</math>; and</p> <p>(b) applying a second wavelength of laser light to at least a portion of the structurally weakened substrate surface having an intermediate surface roughness, <math>R_i</math>, to remove the structurally weakened surface to modify the surface of at least a part of said portion to a final surface roughness, <math>R_F</math>, wherein said first and second wavelengths of laser light are different wavelengths of laser light.</p>	<p>An apparatus for processing a diamond film substrate, said apparatus comprising:</p> <p>(a) a holder for receiving the diamond film substrate; and</p> <p>(b) a laser system configured to first direct a first wavelength of laser light toward the holder at a diamond film substrate having a surface, said surface having an initial surface roughness, <math>R_0</math>, to both evaporate a portion of the substrate surface and create a structurally weakened surface having an intermediate surface roughness, <math>R_i</math>; and</p> <p>further configured to subsequently direct a second wavelength of laser light to at least a portion of the structurally weakened substrate surface having an intermediate surface roughness, <math>R_i</math>, to remove the structurally weakened surface to modify the surface of at least a part of said portion to a final surface roughness, <math>R_F</math>, wherein said first and second wavelengths of laser light are different wavelengths of laser light.</p>

If it would be of assistance in resolving any issues in this application, the Examiner is kindly invited to contact applicant's attorney Mark Gilbreth at (713) 227-1200, or in his absence Dr. Mary Gilbreth.

Respectfully submitted,



J. M. (Mark) Gilbreth, Registration No. 33,388  
Attorney for Applicants

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GILBRETH & ASSOCIATES, P.C.  
PO Box 61305  
HOUSTON, TEXAS 77208-1305  
713/227-1200